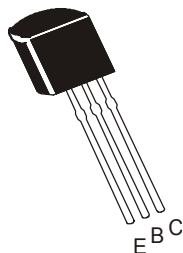


PNP SILICON TRANSISTOR



CSA 643

TO-92
Plastic Package

Audio Frequency General Purpose Power Amplifier Application

Complementary CSD 261

ABSOLUTE MAXIMUM RATINGS (Ta=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	VALUE	UNIT
Collector Emitter Voltage	V_{CEO}	20	V
Collector Base Voltage	BV_{CBO}	40	V
Emitter Base Voltage	V_{EBO}	5	V
Collector Current Continuous	I_C	500	mA
Peak	I_{CM}	700	mA
Collector Power Dissipation	P_C	500	mW
Derate Above 25°C		4.0	mW/°C
Operating and Storage Junction Temperature Range	T_j, T_{stg}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (Ta=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNIT
Collector Emitter Breakdown Voltage	BV_{CEO}	$I_C=10mA, I_B=0$	20		V
Collector Base Breakdown Voltage	BV_{CBO}	$I_C=100\mu A, I_B=0$	40		V
Emitter Base Breakdown Voltage	BV_{EBO}	$I_E=100\mu A, I_C=0$	>5		V
Collector Cut off Current	I_{CBO}	$V_{CB}=25V, I_E = 0$		0.1	μA
Emitter Cut off Current	I_{EBO}	$V_{EB}=3V, I_C = 0$		0.1	μA
DC Current Gain	h_{FE}	$V_{CE}=1V, I_C=100mA^*$	40	400	
Base Emitter Saturation Voltage	$V_{BE(sat)}^*$	$I_C=500mA, I_B= 50mA^*$		1.3	V
Collector Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=500mA, I_B=50mA^*$		0.4	V

*Pulse Condition: = Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

h_{FE} CLASSIFICATION

R
40-80

O
70-140

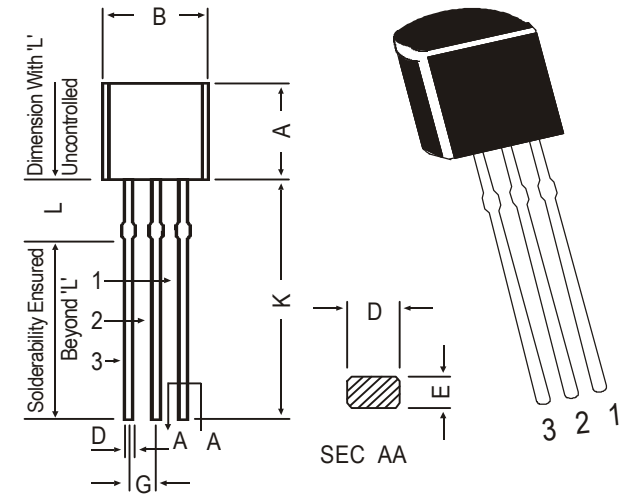
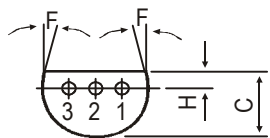
Y
20-240

G
200-400

TO-92
Plastic Package

TO-92 Plastic Package

TO-92 Transistors on Tape and Ammo Pack

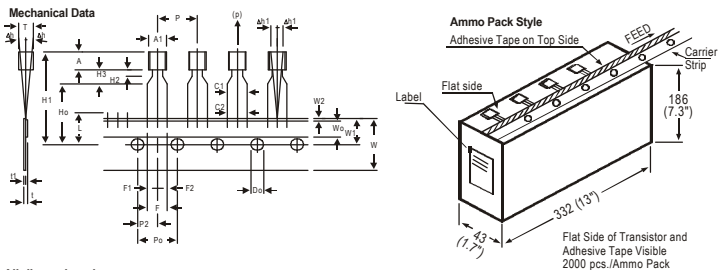


PIN CONFIGURATION

1. COLLECTOR
2. BASE
3. EMITTER

DIM	MIN.	MAX.
A	4.32	5.33
B	4.45	5.20
C	3.18	4.19
D	0.41	0.55
E	0.35	0.50
F	5 DEG	
G	1.14	1.40
H	1.14	1.53
K	12.70	—
L	1.982	2.082

All diminsions in mm.



All dimensions in mm

ITEM	SYMBOL	SPECIFICATION				REMARKS
		MIN.	NOM.	MAX.	TOL.	
BODY WIDTH	A1	4.0	4.8	5.2		CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH
BODY HEIGHT	A	4.8	5.2	5.6		
BODY THICKNESS	T	3.9	4.2	4.5		
PITCH OF COMPONENT	P	12.7	12.7	12.7	± 1.0	
FEED HOLE PITCH	Po				± 0.3	TO BE MEASURED AT BOTTOM OF CLINCH
FEED HOLE CENTRE TO COMPONENT CENTRE	P2	6.35			± 0.4	
DISTANCE BETWEEN OUTER LEADS	F	5.08			+ 0.6 - 0.2	
COMPONENT ALIGNMENT SIDE VIEW	Δh	0	1.0			
COMPONENT ALIGNMENT FRONT VIEW	Δh1	0	1.3			AT TOP OF BODY AT TOP OF BODY
TAPE WIDTH	W	18			± 0.5	
HOLD-DOWN TAPE WIDTH	Wo	6			± 0.2	
HOLE POSITION	W1	9			+ 0.7 - 0.5	
HOLD-DOWN TAPE POSITION	W2	0.5			± 0.2	t1 0.3-0.6
LEAD WIRE CLINCH HEIGHT	Ho	16			± 0.5	
COMPONENT HEIGHT	H1		23.25			
LENGTH OF SNIPPED LEADS	L		11.0			
FEED HOLE DIAMETER	Do	4			± 0.2	t1 0.3-0.6
TOTAL TAPE THICKNESS	t		1.2			
LEAD - TO - LEAD DISTANCE	F1, F2	2.54			+ 0.4 - 0.1	
STAND OFF	H2	0.45		1.45		
CLINCH HEIGHT	H3			3.0		
LEAD PARALLELISM	C1 - C2			0.22		
PULL - OUT FORCE	(P)	6N				

NOTES

1. Maximum alignment deviation between leads will not to be greater than 0.2mm.
2. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
3. Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.
4. There will be no more than three (3) consecutive missing components in a tape.
5. A tape trailer, having at least three feed holes are provided after the last component in a tape.
6. Splices should not interfere with the sprocket feed holes.

Packing Detail

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	12.5 kgs

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